

IN THE CLAIMS

Please cancel claims 21 and 41-42 and amend claims 1, 5, 9, 15 and 17-18 to read as shown below by substituting the claims below for claims having the same number as follows.

Pursuant to 37 C.F.R. §1.121, a marked-up version of the following claims is provided at the end of this Amendment as Exhibit B.

1. (Amended) A device comprising:

a package module including a substrate having a standard package footprint;
an unpackaged semiconductor die directly attached to the package module, the
unpackaged semiconductor die encapsulated onto the package module in a structure having a
substantially rectangular footprint; and
a packaged semiconductor die attached to the package module.

B3

*b not clearly defined in the claim.
Examiner assumed
structure = package module*

5. (Amended) The device as in claim 1, wherein a plurality of packaged semiconductors are attached to the package module.
- B4 (and 9)*

9. (Twice Amended) The device as in claim 1, wherein the encapsulated structure has a footprint greater than the footprint of the unpackaged semiconductor die.
- B5 (and 9)*

15. (Amended) A device comprising:

a package module sized to be interchangeable with standard package sizes;
a graphics-processing die directly attached to the package module, the graphics-
processing die encapsulated on the package module in a structure having a rectangular footprint;
and
a packaged memory die attached to the package module.

B6

17. (Amended) The device as in claim 15, wherein a plurality of packaged memory are attached to the package module.
- B7 (and 5)*

18. (Amended) The device as in claim 15, wherein directly attached includes the graphics processing die being wire bonded to the package module.